

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A resin-coated copper foil, wherein the resin-coated copper foil has the resin layer on one surface of the copper foil, wherein the resin layer has a resin composition as follows:

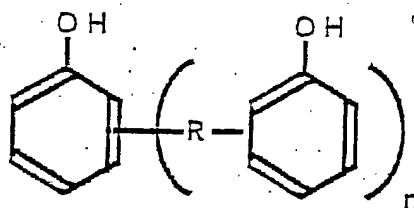
(1) 20 to 70 parts by weight of an epoxy resin

(2) 5 to 30 parts by weight of a high polymer having a crosslinkable functional group in its molecule and a crosslinking agent therefor in combination

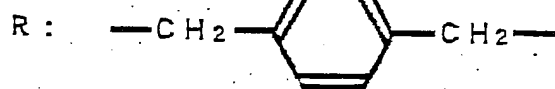
(3) 10 to 60 parts by weight of a compound having a structure shown in

Formula 1:

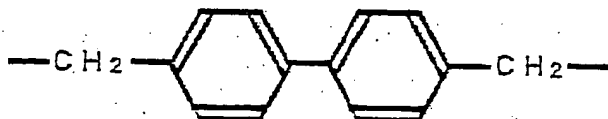
Formula 1



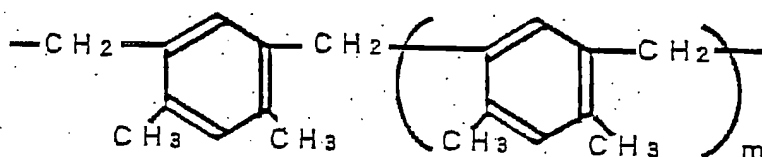
, wherein n is an integer of one or more,



OR



OR



, wherein m is an integer of 0 or greater.

2. (Original) The resin-coated copper foil according to claim 1, wherein the high polymer having a crosslinkable functional group in its molecule and the crosslinking agent therefor are one or more selected from the group consisting of a polyvinyl acetal resin, a phenoxy resin, a polyethersulfone resin, a carboxyl modified acrylonitrile-butadiene resin and an aromatic polyamide resin polymer, which are all soluble in a solvent.

3. (Currently Amended) A multilayer printed wiring board, comprising the resin-coated copper foil according to claim 1 ~~or~~ 2.

4. (New) A multilayer printed wiring board, comprising the resin-coated copper foil according to claim 2.